

1 Product Overview

WBR1D-IPEX is a low-power embedded Wi-Fi and Bluetooth module that Tuya has developed. It consists of a highly integrated RF chip (RTL8720DN) and several peripheral components, with an embedded Wi-Fi network protocol stack, Bluetooth network protocol, and robust library functions. WBR1D-IPEX is embedded with a low-power 32-bit CPU, 512 KB static random-access memory (SRAM), and 4 MB flash memory, and has extensive peripherals.

WBR1D-IPEX is an RTOS platform that integrates all function libraries of the Wi-Fi MAC and TCP/IP protocols. You can develop embedded Wi-Fi products as required.

1.1 Features

- ✧ Embedded low-power 32-bit CPU, which can also function as an application processor
 - Clock rates: 80 MHz and 160 MHz
- ✧ Working voltage: 3.0 V to 3.6 V
- ✧ Peripherals: six GPIOs, two universal asynchronous receivers/transmitters (UARTs), and one analog-to-digital converter (ADC)
- ✧ Wi-Fi connectivity
 - 802.11a/b/g/n 1x1, 2.4 GHz and 5 GHz capable
 - Channels 1 to 14 at 2.4 GHz and channels 36 to 177 at 5 GHz
 - WPA and WPA2 security modes
 - Up to +17 dBm output power in 802.11b mode and up to +15 dBm in 802.11a mode
 - STA, AP, and STA+AP working modes

- Smart and AP network configuration modes for Android and iOS devices
- Onboard IPEX antenna with a gain of 2 dBi at 2.4 GHz and 2.6 dBi at 5 GHz
- Working temperature: -20°C to $+85^{\circ}\text{C}$

1.2 Applications

- ✧ Intelligent building
- ✧ Smart household and home appliances
- ✧ Smart socket and light
- ✧ Industrial wireless control
- ✧ Baby monitor
- ✧ Network camera
- ✧ Intelligent bus

Change History

No.	Date	Change Description	Version After Change
1	2019-10-10	This is the first release.	1.0.0

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2 WBR1D-IPEX Label

Model: module model

P/N: product number

S/N: serial number

CE: European Conformity marking

RoHS: RoHS compliance logo

3.1 Dimensions and Footprint

3.1 Dimensions and Footprint

The WBR1D-IPEX dimensions (H x W x D) are 3.5 mm x 18 mm x 23.5 mm. Figure 3-1 shows the TYWBR1D-IPEX front and rear views.

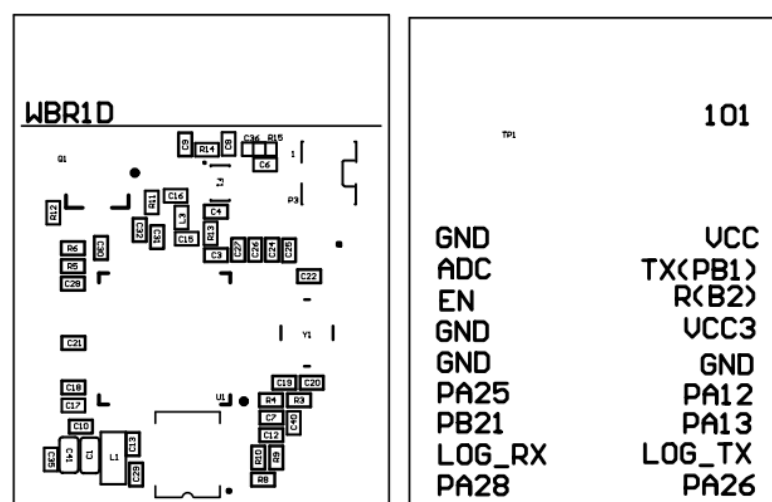


Figure 3-1 WBR1D-IPEX front and rear views

The default dimensional tolerance is ± 0.3 mm, and the tolerance for some measurements is ± 0.1 mm. The PCB thickness is 1.0 ± 0.1 mm.

3.2 Interface Pin Definition

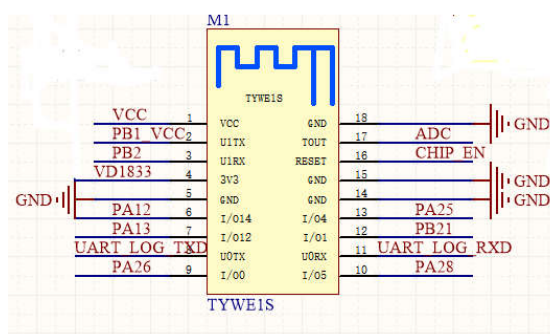


Table 3-1 WBR1D-IPEX interface pins

Pin No.	Symbol	I/O Type	Function
1	VCC	P	UART1 power supply pin
2	U1TX	I/O	UART1_TXD (user-side serial interface)
3	U1RX	I/O	UART1_RXD (user-side serial interface)
4	3V3	P	Power supply pin (3.3 V)
5	GND	P	Power supply reference ground pin
6	IO14	I/O	GPIO_14
7	IO12	I/O	GPIO_12
8	U0TX	I/O	UART0_TXD (used to display the module internal information)
9	IO0	I/O	GPIO_0
10	IO5	I/O	GPIO_5
11	U0RX	I/O	UART0_RXD (used to display the module internal information)
12	IO1	I/O	GPIO_1
13	IO4	I/O	GPIO_4
14	GND	P	Power supply reference ground pin
15	GND	P	Power supply reference ground pin
16	RESET	I/O	External reset pin
17	TOUT	AI	ADC pin
18	GND	P	Power supply reference ground pin

Note:

P indicates power supply pins, **I/O** indicates input/output pins, and **AI** indicates analog input pins.

RESET is only a hardware reset pin and cannot clear the Wi-Fi network configuration.

3.3 Test Pin Definition

Table 3-2 TYWBR1D-IPEX test pins

Pin No.	Symbol	I/O Type	Function
N/A	TEST	Input	Used for the module production test

Note:

Test pins are not recommended.

4 Electrical Parameters

4.1 Absolute Electrical Parameters

Table 4-1 Absolute electrical parameters

Parameter	Description	Minimum Value	Maximum Value	Unit
Ts	Storage temperature	-20	85	°C
VCC	Power supply voltage	-0.3	3.6	V
Static electricity voltage (human body model)	Tamb = 25°C	N/A	2	kV
Static electricity voltage (machine model)	Tamb = 25°C	N/A	0.5	kV

4.2 Electrical Conditions

Table 4-2 Normal electrical conditions

Parameter	Description	Minimum Value	Typical Value	Maximum Value	Unit
Ta	Working temperature	-20	N/A	85	°C
VCC	Power supply voltage	3.0	3.3	3.6	V
V _{IL}	I/O low-level input	-0.3	N/A	VCC x 0.25	V
V _{IH}	I/O high-level input	VCC x 0.75	N/A	VCC	V
V _{OL}	I/O low-level output	N/A	N/A	VCC x 0.1	V
V _{OH}	I/O high-level output	VCC x 0.8	N/A	VCC	V
I _{max}	I/O drive current	N/A	N/A	12	mA

4.3 RF Current Consumption

Table 4-3 Power consumption during constant transmission

Working Status	Parameter	
	Mode	TX Power
TX at 2.4 GHz	802.11b	+17.56 dBm
	802.11g	+18.35 dBm
	802.11n20	+17.43 dBm
	802.11n40	+16.52 dBm
	BLE	+8.66dBm
TX at 5 GHz	802.11a	+16.83 dBm
	802.11n20	+15.87 dBm
	802.11n40	+14.91 dBm

Table 4-4 Power consumption during constant receiving

Working Status	Mode	Rate	Typical Value	Unit
2.4 GHz	802.11b	11 Mbit/s	70	mA
	802.11g	54 Mbit/s	72	mA
	802.11n HT20	MCS7	70	mA
	802.11n HT40	MCS7	73	mA
5 GHz	802.11a	54 Mbit/s	71	mA
	802.11n HT20	MCS7	72	mA
	802.11n HT40	MCS7	76	mA

4.4 Working Current

Table 4-5 WBR1D-IPEX working current

Working Mode	Working Status (Ta = 25°C)	Average Value	Maximum Value	Unit
EZ	The module is in EZ mode, and the Wi-Fi indicator blinks quickly.			mA
AP	The module is in AP mode, and the Wi-Fi indicator blinks slowly.			mA
Connected	The module is connected to the network, and the Wi-Fi indicator is steady on.			mA
Disconnected	The module is disconnected from the network, and the Wi-Fi indicator is steady off.			mA

5 RF Features

5.1 Basic RF Features

Table 5-1 Basic RF features

Parameter	Description
Frequency band	2.412 GHz to 2.484 GHz; 5.18 GHz to 5.885 GHz
Wi-Fi standard	IEEE 802.11a/b/g/n (channels 1 to 14 and 36 to 177)
Data transmission rate	802.11b: 1, 2, 5.5, or 11 (Mbit/s) 802.11a/g: 6, 9, 12, 18, 24, 36, 48, or 54 (Mbit/s) 802.11n: HT20 MCS0 to MCS7 802.11n: HT40 MCS0 to MCS7
Antenna type	IPEX antenna with a gain of 2 dBi at 2.4 GHz and 2.6 dBi at 5 GHz

5.2 TX Performance

Table 5-2 Performance during constant transmission at 2.4 GHz

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11b CCK mode	11 Mbit/s	N/A	17	N/A	dBm
Average RF output power, 802.11g OFDM mode	54 Mbit/s	N/A	16	N/A	dBm
Average RF output power, 802.11n HT20 mode	MCS7	N/A	15	N/A	dBm
Average RF output power, 802.11n HT40 mode	MCS7	N/A	14	N/A	dBm
Frequency error		-10	N/A	+10	ppm
EVM under 802.11b CCK, 11 Mbit/s, 17.5 dBm			-16.5		dB

Parameter	Minimum Value	Typical Value	Maximum Value	Unit
EVM under 802.11g OFDM, 54 Mbit/s, 15.0 dBm		-33.1		dB
EVM under 802.11n OFDM, MCS7, 14.0 dBm		-32.2		dB

Table 5-3 Performance during constant transmission at 5 GHz

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
Average RF output power, 802.11a OFDM mode	54 Mbit/s	N/A	14	N/A	dBm
Average RF output power, 802.11n HT20 mode	MCS7	N/A	13	N/A	dBm
Average RF output power, 802.11n HT40 mode	MCS7	N/A	12	N/A	dBm
Frequency error		-10	N/A	+10	ppm
EVM under 802.11b CCK, 11 Mbit/s, 17.5 dBm			-16.5		dB
EVM under 802.11g OFDM, 54 Mbit/s, 15.0 dBm			-33.1		dB
EVM under 802.11n OFDM, MCS7, 14.0 dBm			-32.2		dB

5.3 RX Performance

Table 5-4 RX sensitivity

Parameter		Minimum Value	Typical Value	Maximum Value	Unit
PER < 8%, 802.11b CCK mode	11 Mbit/s	N/A	-91	N/A	dBm
PER < 10%, 802.11a/g OFDM mode	54 Mbit/s	N/A	-75	N/A	dBm
PER < 10%, 802.11n OFDM mode	HT20 MCS7	N/A	-72	N/A	dBm

6 Antenna Information

6.1 Antenna Type

WBR1D-IPEX uses a IPEX antenna.

6.2 Antenna Connector Specifications

WBR1D-IPEX does use an IPEX antenna connector.

7 Packaging Information and Production Instructions

7.1 Mechanical Dimensions

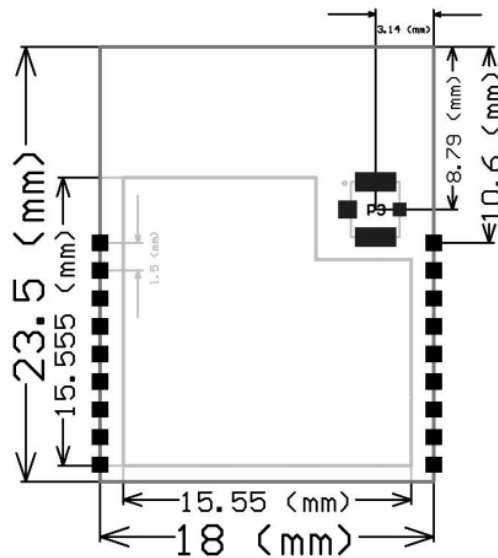


Figure 7-1 WBR1D-IPEX mechanical dimensions

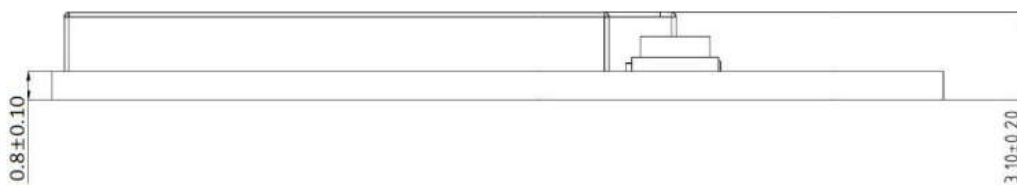


Figure 7-2 Side view

Note:

The default dimensional tolerance is ± 0.3 mm. If a customer has other requirements, clearly specify them in the datasheet after communication.

7.2 Recommended PCB Layout

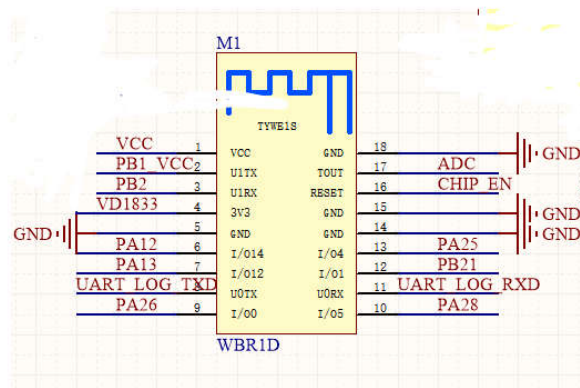


Figure 7-3 WBR1D-IPEX pins

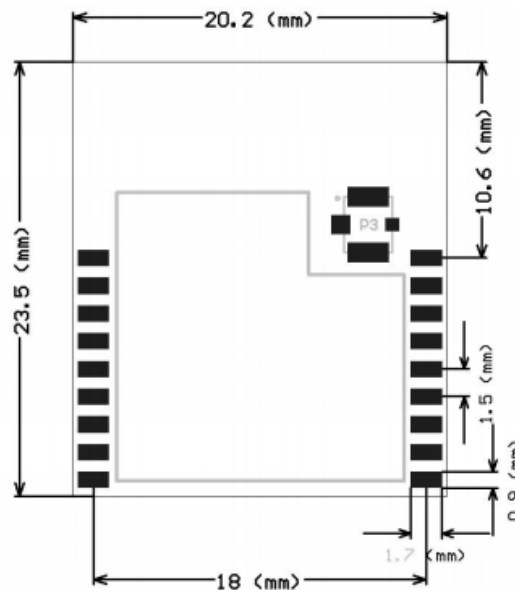


Figure 7-4 Layout of the PCB to which WBR1D-IPEX applies

7.3 Production Instructions

1. Use an SMT placement machine to mount the stamp hole module that Tuya produces onto the PCB within 24 hours after the module is unpacked and the firmware is burned. If not, vacuum pack the module again. Bake the module before mounting it onto the PCB.
 - (1) SMT placement equipment
 - i. Reflow soldering machine
 - ii. Automated optical inspection (AOI) equipment
 - iii. Nozzle with a 6 mm to 8 mm diameter
 - (2) Baking equipment
 - i. Cabinet oven
 - ii. Anti-static heat-resistant trays
 - iii. Anti-static heat-resistant gloves
2. Storage conditions for a delivered module are as follows:
 - (1) The moisture-proof bag is placed in an environment where the temperature is below 30°C and the relative humidity is lower than 70%.
 - (2) The shelf life of a dry-packaged product is six months from the date when the product is packaged and sealed.
 - (3) The package contains a humidity indicator card (HIC).

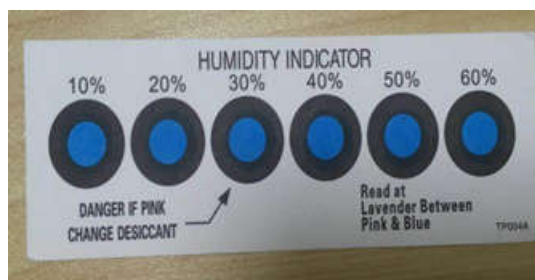


Figure 7-5 HIC for WBR1D-IPEX

3. Bake a module based on HIC status as follows when you unpack the module package:
 - (1) If the 30%, 40%, and 50% circles are blue, bake the module for 2 consecutive

hours.

- (2) If the 30% circle is pink, bake the module for 4 consecutive hours.
- (3) If the 30% and 40% circles are pink, bake the module for 6 consecutive hours.
- (4) If the 30%, 40%, and 50% circles are pink, bake the module for 12 consecutive hours.

4. Baking settings:

- (1) Baking temperature: $125\pm 5^{\circ}\text{C}$
 - (2) Alarm temperature: 130°C
 - (3) SMT placement ready temperature after natural cooling: $< 36^{\circ}\text{C}$
 - (4) Number of drying times: 1
 - (5) Rebaking condition: The module is not soldered within 12 hours after baking.
5. Do not use SMT to process modules that have been unpacked for over three months. Electroless nickel immersion gold (ENIG) is used for the PCBs. If the solder pads are exposed to the air for over three months, they will be oxidized severely and dry joints or solder skips may occur. Tuya is not liable for such problems and consequences.
6. Before SMT placement, take electrostatic discharge (ESD) protective measures.
7. To reduce the reflow defect rate, draw 10% of the products for visual inspection and AOI before first SMT placement to determine a proper oven temperature and component placement method. Draw 5 to 10 modules every hour from subsequent batches for visual inspection and AOI.

7.4 Recommended Oven Temperature Curve

Perform SMT placement based on the following reflow oven temperature curve. The highest temperature is 245°C.

Refer to IPC/JEDEC standard ; Peak Temperature : <250°C ; Number of Times: ≤2 times ;

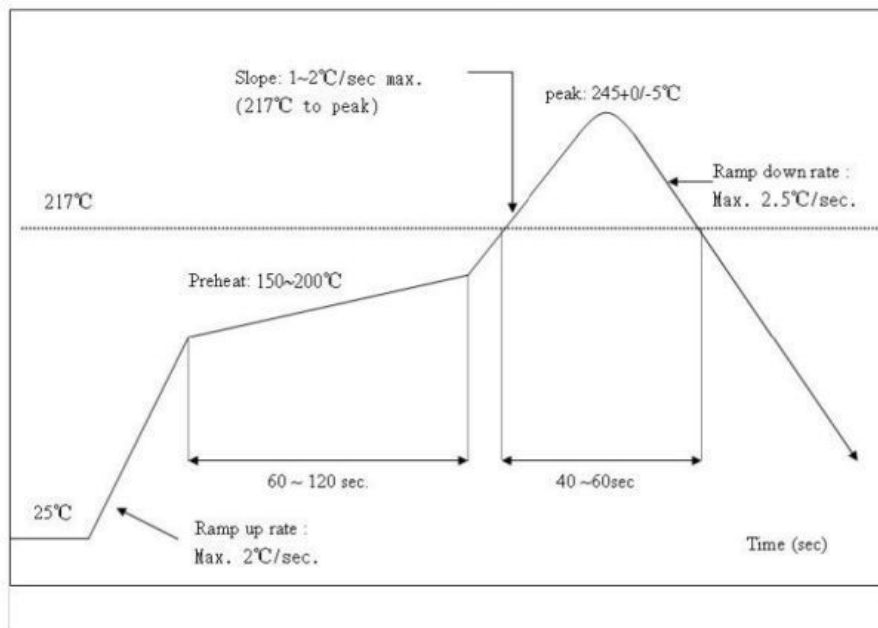


Figure 7-6 Oven temperature curve

7.5 Storage Conditions

	CAUTION This bag contains MOISTURE-SENSITIVE DEVICES	LEVEL <div style="border: 1px solid black; padding: 5px; display: inline-block;"> 3 </div>
If Blank, see adjacent bar code label		
1. Calculated shelf life in sealed bag: 12 months at < 40°C and < 90% relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must		
a) Mounted within: <u>168</u> hrs. of factory conditions <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
≤ 30°C/60%RH, OR		
b) Stored at <10% RH		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card is > 10% when read at 23 ± 5°C		
b) 3a or 3b not met.		
5. If baking is required, devices may be baked for 48 hrs. at 125 ± 5°C		
Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ <small style="display: block; text-align: right;">If Blank, see adjacent bar code label</small>		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

8 Appendix: Statement

Federal Communications Commission (FCC) Declaration of Conformity

FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate this equipment.

This device complies with Part 15 of the FCC Rules.

Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

This device and its antenna(s) must not be co-located or operating in conjunction with any other antenna or transmitter.

15.105 Information to the user.

(b) For a Class B digital device or peripheral, the instructions furnished the user shall include the following or similar statement, placed in a prominent location in the text of the manual:

Note:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules.

These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20 cm between the radiator and your body.

This device have got a FCC ID: 2ANDL-WBR1D-IPEX. The final end product must be labeled in a visible area with the following: "Contains Transmitter Module FCC ID:2ANDL-WBR1D-IPEX"

This device is intended only for OEM integrators under the following conditions:

1) The antenna must be installed such that 20cm is maintained between the antenna and users, and

2) The transmitter module may not be co-located with any other transmitter or antenna.

As long as 2 conditions above are met, further transmitter test will not be required.

However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this module installed.

Declaration of Conformity European notice



Hereby, Hangzhou Tuya Information Technology Co., Ltd. declares that this Wi-Fi module product is in compliance with essential requirements and other relevant provisions of Directive 2014/53/EC. A copy of the Declaration of conformity can be found at <https://www.tuya.com>.



This product must not be disposed of as normal household waste, in accordance with EU directive for waste electrical and electronic equipment (WEEE- 2012/19/EU). Instead, it should be disposed of by returning it to the point of sale, or to a municipal recycling collection point.

The device could be used with a separation distance of 20cm to the human body.

The device is restricted to indoor use only when operating in the 5150 to 5350 MHz frequency range.

	AT	BE	BG	HR	CY	CZ	DK
	EE	FI	FR	DE	EL	HU	IE
	IT	LV	LT	LU	MT	NL	PL
	PT	RO	SK	SI	ES	SE	UK